SN54150, SN54151A, SN54LS151, SN54S151, SN74150, SN74151A, SN74LS151, SN74S151 DATA SELECTORS/MULTIPLEXERS

- '150 Selects One-of-Sixteen Data Sources
- Others Select One-of-Eight Data Sources
- All Perform Parallel-to-Serial Conversion
- All Permit Multiplexing from N Lines to One Line
- Also For Use as Boolean Function Generator
- Input-Clamping Diodes Simplify System Design
- Fully Compatible with Most TTL Circuits

ТҮРЕ	TYPICAL AVERAGE PROPAGATION DELAY TIME DATA INPUT TO W OUTPUT	TYPICAL POWER DISSIPATION
'150	13 ns	200 mW
ʻ151A	8 ns	145 mW
' LS1 51	13 ns	30 mW
'S151	4.5 ns	225 mW

description

These monolithic data selectors/multiplexers contain full on-chip binary decoding to select the desired data source. The '150 selects one-of-sixteen data sources; the '151A, 'LS151, and 'S151 select one-of-eight data sources. The '150, '151A, 'LS151, and 'S151 have a strobe input which must be at a low logic level to enable these devices. A high level at the strobe forces the W output high, and the Y output (as applicable) low.

The '150 has only an inverted W output; the '151A, 'LS151, and 'S151 feature complementary W and Y outputs.

The '151A and '152A incorporate address buffers that have symmetrical propagation delay times through the complementary paths. This reduces the possibility of transients occurring at the output(s) due to changes made at the select inputs, even when the '151A outputs are enabled (i.e., strobe low).

-								
	DECE	MBER	1972	-RE\	/ISED	MARC	H 198	Į
								-

SN54150 J . SN74150	
(TOP)	
E7 [1]	Z4 VCC
E6 [] 2	23 E8
E0 [] 2 E5 [] 3	23 E9
E 4 □ 4	21 E10
E3 []5	20 E11
E2 []6	19 E12
E1 17	18 E13
E La G Da	
W [] 10	15 A
GND [12	_13 □ C
SN54151A, SN54LS151, SN54	
SN74151A	
SN74LS151, SN74S151	
	/IEW)
D3 🛛 1 🗸	16 VCC
D2 🗍 2	15 🗋 D4
D1 🔲 3	14 🗋 D5
D0 🗍 4	13 D6
Y 🗖 5	12 D7
₩ 🗍 6	11 🗍 A
ច្បីរ	10 8
	эПс
4	
SN54LS151, SN54S1	51 FK PACKAGE
(TOP V	IEW)
	о С
N D D D D D D D D D D D D D D D D D D D	D 4C
	20 19
	18 D5
D0 [] 5	17UD6
Y D 7	15 D7
WUB	14 U A
	12 13
ျဖ ရ ပွ	Um
Z Z U	

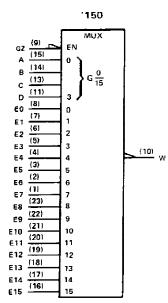
NC - No internal connection

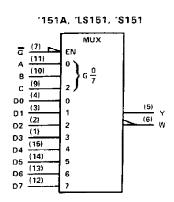
PRODUCTION DATA documents contain information current as of publication date. Products conform to specifications per the terms of Taxas Instruments standard warranty. Production processing does not necessarily include testing of all parameters.



SN54150, SN54151A, SN54LS151, SN54S151, SN74150, SN74151A, SN74LS151, SN74S151 DATA SELECTORS/MULTIPLEXERS

logic symbols[†]





[†]These symbols are in accordance with ANSI/IEEE Std. 91-1984 and IEC Publication 617-12. Pin numbers shown are D, J, N, and W packages.

		FUI	NCTI	ON TABL	E
		IN	PUT	5	OUTPUT
[SEL	ECT		STROBE	
D	С	в	A	Ğ	W
х	X	х	х	н	н
L	L	L	L	L	ĒÕ
L	L	L	н	L	E1
L	L	H	L	L	E2
L	L	н	н	L	Ē3
L	н	L	L	L	Ē4
L	н	L	H	L	E5
L	н	н	L	L	E6
L	н	н	н	L	Ē7
н	L	L	L	L	68
н	L	L	H	L	Ē9
н	L	н	L	L	E10
н	L	н	н	L	E11
н	н	L	L	L	E12
н	н	L	н	L	E13
н	н	н	L	L	E14
н	н	н	н	L	E15

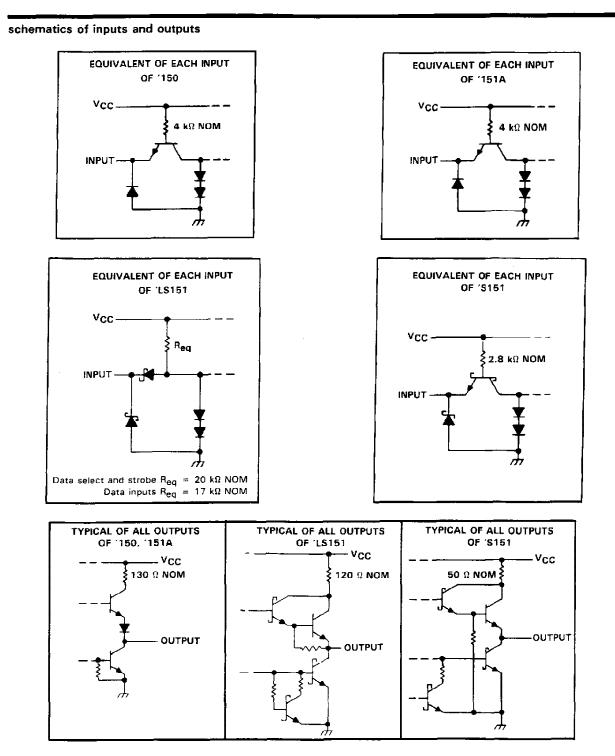
'150

151A, LS151, S151 FUNCTION TABLE

	H	VPUT	rs	OUT	PUTS								
s	ELEC	т	STROBE		w								
С	8	A	Ğ	¥	**								
X	х	X	н	L	н								
L	L	L	L	DO	00								
L	L	н	L	D1	D1								
L	н	Ł	L	D2	D2								
L	н	н	L	D3	D3								
н	L	L	L	D4	D4								
н	L	н	L	D5	D5								
н	н	L	L	D6	D6								
н	н	н	L	D7	D7								



SN54150, SN54151A, SN54LS151, SN54S151 SN74150, SN74151A, SN74LS151, SN74S151 DATA SELECTORS/MULTIPLEXERS



TEXAS V INSTRUMENTS

SN54150, SN54151A, SN74150, SN74151A DATA SELECTORS/MULTIPLEXERS

recommended operating conditions

		SN54'			SN74'		
	MIN	NOM	MAX	MIN	NOM	MAX	UNIT
Supply voltage, VCC	4.5	5	5.5	4.75	5	5.25	V
High-level output current, IOH			-800			-800	μA
Law-level output current, IOL			16			16	mΑ
Operating free-air temperature, TA	-55		125	0		70	Ċ

electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

		TEST CONDIT	uquat	′150				'151A		
	PARAMETER	IEST CONDIT		MIN	TYP [‡]	MAX	MIN	TYP [‡]	MAX	UNIT
VIH	High-level input voltage			2			2			V
VIL	Low-level input voltage					0.8			0.8	V
VIK	Input clamp voltage	V _{CC} = MIN, I _I =	-8 mA		· · ·	- 1.5			-1.5	v
∨он	High-level output voltage	$V_{CC} = MIN, V_{IH}$ $V_{IL} = 0.8 V, I_{OH}$	1	2.4	3.4		2.4	3.4		v
V _{OL}	Low-level output voltage	$V_{CC} = MIN, V_{IH}$ $V_{IL} = 0.8 V, I_{OL}$			0.2	0.4		0.2	0.4	v
4	Input current at maximum input voltage	$V_{CC} = MAX, V_{I} =$	= 5.5 V			1			1	mA
ЧH	High-level input current	$V_{CC} = MAX, V_{I} =$	= 2.4 V			40			40	μA
hL	Low-level input current	$V_{CC} = MAX, V_{I} =$	= 0.4 V			-1.6			-1.6	mA
	a t		SN54'	- 20		- 55	- 20		- 55	
los	Short-circuit output current ^s	V _{CC} = MAX	SN74'	- 18		- 55	- 18		- 55	mA
'cc	Supply current	VCC = MAX, See	Note 3		40	68		29	48	mA

[†] For conditions shown as MIN or MAX, use the appropriate value specified under recommended operating conditions for the applicable device type. ⁴ All typical values at $V_{CC} = 5 V$, $T_A = 25^{\circ}C$. ⁵ Not more than one output of the '151A should be shorted at a time.

NOTE 3: ICC is measured with the strobe and data select inputs at 4.5 V, all other inputs and outputs open.

switching characteristics, VCC = 5 V, TA = 25°C

our of	FROM	то	TEST		'150			151/	A,	
PARAMETER	(INPUT)	(OUTPUT)	CONDITIONS	MIN	TYP	MAX	MIN	ТҮР	MAX	
^t PLH	A, B, or C	Y						25	38	
^t PHL	(4 levels)	,						25	38	- 115
tPLH	A, B, C, or D (3 levels)	W			23	35	_	17	26	ns
^t PHL					22	33		19	30	
τ Ρ ŁΗ	Strobe G	Y	С _L = 15 рF,					21	33	ns
^t PHL	Strobe G							22	33	1.13
^t PLH	Strobe G	w	See Note 4 j		15.5	24		14	21	
^t PHL	Strobe G	~~			21	30		15	23	ns
tPLH	D0 thru D7	Y						13	20	
τρητ		Ŧ						18	27	ns
tPLH	E0 thru E15, or	w			8.5	14		8	14	
^t PHL	D0 thru D7	**			13	20		8	14	ns

\$ tpLH = propagation delay time, low-to-high-level output tpHL = propagation delay time, high-to-low-level output NOTE 4: Load circuits and voltage waveforms are shown in Section 1.

recommended operating conditions

	s	SN54LS151			SN74LS151			
	MIN	NOM	MAX	MIN	NOM	MAX	UNIT	
Supply voltage, VCC	4.5	5	b,b	4.75	5	5.25	Y	
High-level output current, IOH			-400			-400	μA	
Low-level output current, IOL			4			8	mA	
Operating free-air temperature, T _A	5		125	0		70	C	

electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

		TEST CONDITIONS [†]	s	SN54LS151			N74LS1	51	
	PARAMETER	TEST CONDITIONS'	MIN	τγ₽‡	MAX	MIN	TYP [‡]	MAX	UNIT
ViH	High-level input voltage		2			2			v
VIL	Low-level input voltage		1		0.7			0.B	V
VIK	Input clamp voltage	$V_{CC} = MIN$, $I_{f} = -18 \text{ mA}$			- 1.5			-1.5	V
∨он	High-level output voltage	$V_{CC} = MIN, V_{IH} = 2 V,$ $V_{IL} = V_{IL}max, I_{OH} = -400 \ \mu A$	2.5	3,4		2.7	3.4		v
		$V_{CC} = MIN, V_{IH} = 2V, I_{OL} = 4 mA$		0.25	0.4		0.25	0.4	
VOL	Low-level output voltage	VIL = VILmax					0.35	0.5	V
ł	Input current at maximum input voltage	$V_{CC} = MAX, V_{\uparrow} = 7 V$			0.1			0.1	mA
Чн	High-level input current	V _{CC} = MAX, V ₁ = 2.7 V	1		20			20	μΑ
կլ	Low-level input current	$V_{CC} = MAX, V_I = 0.4 V$			-0.4			-0.4	mA
los	Short-circuit output current§	V _{CC} = MAX	- 20		- 100	- 20		- 100	mA
lcc	Supply current	V _{CC} = MAX, Outputs open, All inputs at 4.5 V		6.0	10		6.0	10	mA

[†] For conditions shown as MIN or MAX, use the appropriate value specified under recommended operating conditions for the applicable device type. [‡] All typical values are at V_{CC} = 5 V, T_A = 25 °C. [§] Not more than one output should be shorted at a time and duration of short-circuit should not exceed one second.

switching characteristics, V_{CC} = 5 V, T_A 25 °C

PARAMETER¶	FROM (INPUT)	TO (OUTPUT)	TEST CONDITIONS	MIN TYP	MAX	דואט	
^t PLH	A, B, or C	Y		27	43		
^t PHL	(4 levels)	r		18	30	ns	
^t PLH	A, B, or C	W	1	14	23		
tPHL	(3 levels)	¥¥	 Сц = 15 рF.	20	32	ns	
^t PLH	Strobe G	Y		26	42		
tPHL		T		20	32	2 115	
^t PLH	Strobe G	w	R _L – 2 kΩ, See Note 4	15	24		
tPHL	SHODE G	vv	VV See Note 4	18	30	ns	
tplh			1	20	32		
tPHL	- Any D	Y		16	26	ns	
^t PLH	A	w		13	21		
tPHL	- Any D	vv		12	20	05	



SN54S151, SN74S151 DATA SELECTORS/MULTIPLEXERS

recommended operating conditions

	\$	SN54S151				SN74S151			
	MIN	NOM	MAX	MIN	NOM	MAX			
Supply voltage, VCC	4.5	5	5.5	4.75	5	5.25	V		
High-level output current, IOH			-t			-1	mA		
Low-level output current, IOL			20			20	mΑ		
Operating free-air temperature, TA	55		125	0		70	°C		

electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

	PARAMETER	TEST CONDITIONS [†]		MIN	ТҮР‡	MAX	UNIT
ViH	High-level input voltage			2			v
VIL	Low-level input voltage					0.8	V
Vik	Input clamp voltage	$V_{CC} = MIN, I_I = -18 \text{ mA}$				-1.2	v
∨он	High-level output voltage	$V_{CC} = MIN, V_{IH} = 2V,$	SN54S151	2.5	3.4		
		VIL = 0.8 V, I _{OH} = -1 mA	SN74S151	2.7	3.4		v
¥		VCC = MIN, V(H = 2 V,	A			0.5	v
VOL	Low-level output voltage	VIL = 0.8 V, IOL = 20 mA					ľ
4	Input current at maximum input voltage	V _{CC} = MAX, V ₁ = 5.5 V				1	mA
ЧĤ	High-level input current	V _{CC} = MAX, V _I = 2.7 V				50	μA
ΊL	Low-level input current	V _{CC} - MAX, VI = 0.5 V				-2	ΜM
los	Short-circuit output current §	V _{CC} = MAX		-40		-100	mA
lcc	Supply current	V _{CC} = MAX, All inputs at 4.5 V, All outputs open			45	70	mA

[†]For conditions shown as MIN or MAX, use the appropriate value specified under recommended operating conditions for the applicable device type.

type. ‡All typical values are at $V_{CC} = 5 V$, $T_A = 25^{\circ}C$. §Not more than one output should be shorted at a time, and duration of the short-circuit should not exceed one second.

switching characteristics. VCC = 5 V. TA 25°C

PARAMETER	FROM (INPUT)	TO (OUTPUT)	TEST CONDITIONS	MIN	TYP	МАХ	UNIT
tPLH	A, B, or C	Y			12	18	
^t PHL	(4 leveis)	T T	1		12	18	ns
t p lh	A, B, or C	W	-		10	15	ns
[†] PHL	(3 levels)		CL = 15 pF, RL - 280 kΩ, See Note 4		9	13.5	
tPLH	Any D	Y			8	12	
^t PHL	Any D	•			8	12	ns
tPLH	- Any D	w			4.5	7	ns
^t PHL					4.5	7	
tplH	Strobe G	Y			11	16.5	
tphL		Ť			12	18	
tPLH	- Strobe G]		9	13	
tPHL		w			8.5	12	กร





1-Jun-2012

PACKAGING INFORMATION

Orderable Device	Status ⁽¹⁾	Package Type	Package Drawing	Pins	Package Qty	Eco Plan ⁽²⁾	Lead/ Ball Finish	MSL Peak Temp ⁽³⁾	Samples (Requires Login)
5962-9558001QJA	ACTIVE	CDIP	J	24	1	TBD	Call TI	Call TI	
5962-9558001QKA	ACTIVE	CFP	W	24	1	TBD	Call TI	Call TI	
5962-9558001QKA	ACTIVE	CFP	W	24	1	TBD	Call TI	Call TI	
5962-9751601QCA	OBSOLETE	CDIP	J	14		TBD	Call TI	Call TI	
76010012A	ACTIVE	LCCC	FK	20	1	TBD	Call TI	Call TI	
76010012A	ACTIVE	LCCC	FK	20	1	TBD	Call TI	Call TI	
7601001EA	ACTIVE	CDIP	J	16	1	TBD	Call TI	Call TI	
7601001EA	ACTIVE	CDIP	J	16	1	TBD	Call TI	Call TI	
7601001FA	NRND	CFP	W	16	1	TBD	Call TI	Call TI	
7601001FA	NRND	CFP	W	16	1	TBD	Call TI	Call TI	
JM38510/01401BKA	ACTIVE	CFP	W	24	1	TBD	A42	N / A for Pkg Type	
JM38510/01401BKA	ACTIVE	CFP	W	24	1	TBD	A42	N / A for Pkg Type	
JM38510/07901BEA	ACTIVE	CDIP	J	16	1	TBD	A42	N / A for Pkg Type	
JM38510/07901BFA	ACTIVE	CFP	W	16	1	TBD	A42	N / A for Pkg Type	
JM38510/30901B2A	ACTIVE	LCCC	FK	20	1	TBD	POST-PLATE	N / A for Pkg Type	
JM38510/30901B2A	ACTIVE	LCCC	FK	20	1	TBD	POST-PLATE	N / A for Pkg Type	
JM38510/30901BEA	ACTIVE	CDIP	J	16	1	TBD	A42	N / A for Pkg Type	
JM38510/30901BEA	ACTIVE	CDIP	J	16	1	TBD	A42	N / A for Pkg Type	
JM38510/30901BFA	ACTIVE	CFP	W	16	1	TBD	A42	N / A for Pkg Type	
JM38510/30901BFA	ACTIVE	CFP	W	16	1	TBD	A42	N / A for Pkg Type	
M38510/01401BKA	ACTIVE	CFP	W	24	1	TBD	A42	N / A for Pkg Type	
M38510/01401BKA	ACTIVE	CFP	W	24	1	TBD	A42	N / A for Pkg Type	
M38510/07901BEA	ACTIVE	CDIP	J	16	1	TBD	A42	N / A for Pkg Type	
M38510/07901BFA	ACTIVE	CFP	W	16	1	TBD	A42	N / A for Pkg Type	
M38510/30901B2A	ACTIVE	LCCC	FK	20	1	TBD	POST-PLATE	N / A for Pkg Type	
M38510/30901B2A	ACTIVE	LCCC	FK	20	1	TBD	POST-PLATE	N / A for Pkg Type	
M38510/30901BEA	ACTIVE	CDIP	J	16	1	TBD	A42	N / A for Pkg Type	
M38510/30901BEA	ACTIVE	CDIP	J	16	1	TBD	A42	N / A for Pkg Type	
M38510/30901BFA	ACTIVE	CFP	W	16	1	TBD	A42	N / A for Pkg Type	
M38510/30901BFA	ACTIVE	CFP	W	16	1	TBD	A42	N / A for Pkg Type	



1-Jun-2012

Orderable Device	Status ⁽¹⁾	Package Type	Package Drawing	Pins	Package Qty	Eco Plan ⁽²⁾	Lead/ Ball Finish	MSL Peak Temp ⁽³⁾	Samples (Requires Login)
SN54150J	ACTIVE	CDIP	J	24	1	TBD	Call TI	N / A for Pkg Type	
SN54150J	ACTIVE	CDIP	J	24	1	TBD	Call TI	N / A for Pkg Type	
SN54LS151J	ACTIVE	CDIP	J	16	1	TBD	A42	N / A for Pkg Type	
SN54LS151J	ACTIVE	CDIP	J	16	1	TBD	A42	N / A for Pkg Type	
SN54S151J	ACTIVE	CDIP	J	16	1	TBD	A42	N / A for Pkg Type	
SN54S15J	OBSOLETE	CDIP	J	14		TBD	Call TI	Call TI	
SN74150N	ACTIVE	PDIP	Ν	24	15	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type	
SN74150N	ACTIVE	PDIP	Ν	24	15	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type	
SN74150NE4	ACTIVE	PDIP	Ν	24	15	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type	
SN74150NE4	ACTIVE	PDIP	Ν	24	15	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type	
SN74151AN	OBSOLETE	PDIP	Ν	16		TBD	Call TI	Call TI	
SN74151AN	OBSOLETE	PDIP	Ν	16		TBD	Call TI	Call TI	
SN74LS151D	ACTIVE	SOIC	D	16	40	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	
SN74LS151D	ACTIVE	SOIC	D	16	40	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	
SN74LS151DE4	ACTIVE	SOIC	D	16	40	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	
SN74LS151DE4	ACTIVE	SOIC	D	16	40	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	
SN74LS151DG4	ACTIVE	SOIC	D	16	40	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	
SN74LS151DG4	ACTIVE	SOIC	D	16	40	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	
SN74LS151DR	ACTIVE	SOIC	D	16	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	
SN74LS151DR	ACTIVE	SOIC	D	16	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	
SN74LS151DRE4	ACTIVE	SOIC	D	16	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	
SN74LS151DRE4	ACTIVE	SOIC	D	16	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	
SN74LS151DRG4	ACTIVE	SOIC	D	16	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	



1-Jun-2012

Orderable Device	Status ⁽¹⁾	Package Type	Package Drawing	Pins	Package Qty	Eco Plan ⁽²⁾	Lead/ Ball Finish	MSL Peak Temp ⁽³⁾	Samples (Requires Login)
SN74LS151DRG4	ACTIVE	SOIC	D	16	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	
SN74LS151J	OBSOLETE	CDIP	J	16		TBD	Call TI	Call TI	
SN74LS151J	OBSOLETE	CDIP	J	16		TBD	Call TI	Call TI	
SN74LS151N	ACTIVE	PDIP	Ν	16	25	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type	
SN74LS151N	ACTIVE	PDIP	Ν	16	25	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type	
SN74LS151N3	OBSOLETE	PDIP	Ν	16		TBD	Call TI	Call TI	
SN74LS151N3	OBSOLETE	PDIP	Ν	16		TBD	Call TI	Call TI	
SN74LS151NE4	ACTIVE	PDIP	Ν	16	25	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type	
SN74LS151NE4	ACTIVE	PDIP	Ν	16	25	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type	
SN74LS151NSR	ACTIVE	SO	NS	16	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	
SN74LS151NSR	ACTIVE	SO	NS	16	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	
SN74LS151NSRE4	ACTIVE	SO	NS	16	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	
SN74LS151NSRE4	ACTIVE	SO	NS	16	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	
SN74LS151NSRG4	ACTIVE	SO	NS	16	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	
SN74LS151NSRG4	ACTIVE	SO	NS	16	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	
SN74S151N	ACTIVE	PDIP	Ν	16	25	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type	
SN74S151N	ACTIVE	PDIP	Ν	16	25	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type	
SN74S151N3	OBSOLETE	PDIP	Ν	16		TBD	Call TI	Call TI	
SN74S151N3	OBSOLETE	PDIP	Ν	16		TBD	Call TI	Call TI	
SN74S151NE4	ACTIVE	PDIP	Ν	16	25	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type	
SN74S151NE4	ACTIVE	PDIP	Ν	16	25	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type	
SNJ54150J	ACTIVE	CDIP	J	24	1	TBD	Call TI	N / A for Pkg Type	
SNJ54150J	ACTIVE	CDIP	J	24	1	TBD	Call TI	N / A for Pkg Type	
SNJ54150W	ACTIVE	CFP	W	24	1	TBD	A42	N / A for Pkg Type	
SNJ54150W	ACTIVE	CFP	W	24	1	TBD	A42	N / A for Pkg Type	
SNJ54LS151FK	ACTIVE	LCCC	FK	20	1	TBD	POST-PLATE	N / A for Pkg Type	



Orderable Device	Status ⁽¹⁾	Package Type	Package Drawing	Pins	Package Qty	Eco Plan ⁽²⁾	Lead/ Ball Finish	MSL Peak Temp ⁽³⁾	Samples (Requires Login)
SNJ54LS151FK	ACTIVE	LCCC	FK	20	1	TBD	POST-PLATE	N / A for Pkg Type	
SNJ54LS151J	ACTIVE	CDIP	J	16	1	TBD	A42	N / A for Pkg Type	
SNJ54LS151J	ACTIVE	CDIP	J	16	1	TBD	A42	N / A for Pkg Type	
SNJ54LS151W	NRND	CFP	W	16	1	TBD	A42	N / A for Pkg Type	
SNJ54LS151W	NRND	CFP	W	16	1	TBD	A42	N / A for Pkg Type	
SNJ54S151FK	ACTIVE	LCCC	FK	20	1	TBD	POST-PLATE	N / A for Pkg Type	
SNJ54S151J	ACTIVE	CDIP	J	16	1	TBD	A42	N / A for Pkg Type	
SNJ54S151W	ACTIVE	CFP	W	16	1	TBD	A42	N / A for Pkg Type	
SNJ54S15FK	OBSOLETE	LCCC	FK	20		TBD	Call TI	Call TI	
SNJ54S15J	OBSOLETE	E CDIP	J	14		TBD	Call TI	Call TI	
SNJ54S15W	OBSOLETE	CFP	W	14		TBD	Call TI	Call TI	

⁽¹⁾ The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

OBSOLETE: TI has discontinued the production of the device.

(2) Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check http://www.ti.com/productcontent for the latest availability information and additional product content details.

TBD: The Pb-Free/Green conversion plan has not been defined.

Pb-Free (RoHS): TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.

Pb-Free (RoHS Exempt): This component has a RoHS exemption for either 1) lead-based flip-chip solder bumps used between the die and package, or 2) lead-based die adhesive used between the die and leadframe. The component is otherwise considered Pb-Free (RoHS compatible) as defined above.

Green (RoHS & no Sb/Br): TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

⁽³⁾ MSL, Peak Temp. -- The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

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PACKAGE OPTION ADDENDUM



www.ti.com

1-Jun-2012

OTHER QUALIFIED VERSIONS OF SN54150, SN54LS151, SN54S15, SN54S151, SN74150, SN74LS151, SN74S151 :

• Catalog: SN74150, SN74LS151, SN74S15, SN74S151

• Military: SN54150, SN54LS151, SN54S151

NOTE: Qualified Version Definitions:

- Catalog TI's standard catalog product
- Military QML certified for Military and Defense Applications

PACKAGE MATERIALS INFORMATION

www.ti.com

TAPE AND REEL INFORMATION

REEL DIMENSIONS

TEXAS INSTRUMENTS





TAPE AND REEL INFORMATION

TAPE DIMENSIONS



A0	Dimension designed to accommodate the component width
B0	Dimension designed to accommodate the component length
K0	Dimension designed to accommodate the component thickness
W	Overall width of the carrier tape
P1	Pitch between successive cavity centers

1	All dimensions are nominal												
	Device	Package Type	Package Drawing		SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
	SN74LS151DR	SOIC	D	16	2500	330.0	16.4	6.5	10.3	2.1	8.0	16.0	Q1
	SN74LS151NSR	SO	NS	16	2000	330.0	16.4	8.2	10.5	2.5	12.0	16.0	Q1

TEXAS INSTRUMENTS

www.ti.com

PACKAGE MATERIALS INFORMATION

14-Jul-2012



*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
SN74LS151DR	SOIC	D	16	2500	333.2	345.9	28.6
SN74LS151NSR	SO	NS	16	2000	367.0	367.0	38.0

MCDI004A - JANUARY 1995 - REVISED NOVEMBER 1997

CERAMIC DUAL-IN-LINE PACKAGE

J (R-GDIP-T**)



NOTES: A. All linear dimensions are in inches (millimeters).

- B. This drawing is subject to change without notice.
- C. Window (lens) added to this group of packages (24-, 28-, 32-, 40-pin).
- D. This package can be hermetically sealed with a ceramic lid using glass frit.
- E. Index point is provided on cap for terminal identification.



J (R-GDIP-T**) 14 LEADS SHOWN

CERAMIC DUAL IN-LINE PACKAGE



NOTES: A. All linear dimensions are in inches (millimeters).

- B. This drawing is subject to change without notice.
- C. This package is hermetically sealed with a ceramic lid using glass frit.
- D. Index point is provided on cap for terminal identification only on press ceramic glass frit seal only.
- E. Falls within MIL STD 1835 GDIP1-T14, GDIP1-T16, GDIP1-T18 and GDIP1-T20.

W (R-GDFP-F16)

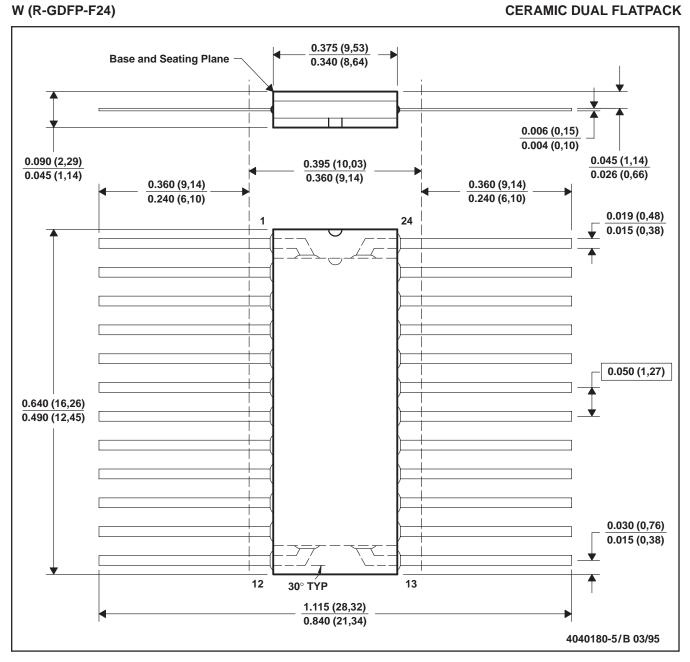
CERAMIC DUAL FLATPACK



- A. All linear dimensions are in inches (millimeters).
 - B. This drawing is subject to change without notice.
 - C. This package can be hermetically sealed with a ceramic lid using glass frit.
 - D. Index point is provided on cap for terminal identification only.
 - E. Falls within MIL STD 1835 GDFP1-F16 and JEDEC MO-092AC



MCFP007 - OCTOBER 1994



NOTES: A. All linear dimensions are in inches (millimeters).

B. This drawing is subject to change without notice.

C. This package can be hermetically sealed with a ceramic lid using glass frit.

- D. Falls within MIL-STD-1835 GDFP2-F24 and JEDEC MO-070AD
- E. Index point is provided on cap for terminal identification only.



LEADLESS CERAMIC CHIP CARRIER

FK (S-CQCC-N**) 28 TERMINAL SHOWN



NOTES: A. All linear dimensions are in inches (millimeters).

B. This drawing is subject to change without notice.

- C. This package can be hermetically sealed with a metal lid.
- D. Falls within JEDEC MS-004



N (R-PDIP-T**)

PLASTIC DUAL-IN-LINE PACKAGE

16 PINS SHOWN



NOTES:

- A. All linear dimensions are in inches (millimeters).B. This drawing is subject to change without notice.
- Falls within JEDEC MS-001, except 18 and 20 pin minimum body length (Dim A).
- \triangle The 20 pin end lead shoulder width is a vendor option, either half or full width.



MPDI006B - SEPTEMBER 2001 - REVISED APRIL 2002

N (R-PDIP-T24)

PLASTIC DUAL-IN-LINE



- NOTES: A. All linear dimensions are in inches (millimeters).
 - B. This drawing is subject to change without notice.
 - C. Falls within JEDEC MS-010



MPDI008 - OCTOBER 1994

N (R-PDIP-T**)

PLASTIC DUAL-IN-LINE PACKAGE

24 PIN SHOWN



NOTES: A. All linear dimensions are in inches (millimeters).

- B. This drawing is subject to change without notice.
- C. Falls within JEDEC MS-011
- D. Falls within JEDEC MS-015 (32 pin only)



D (R-PDSO-G16)

PLASTIC SMALL OUTLINE



NOTES: A. All linear dimensions are in inches (millimeters).

- B. This drawing is subject to change without notice.
- Body length does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0.006 (0,15) each side.
- Body width does not include interlead flash. Interlead flash shall not exceed 0.017 (0,43) each side.
- E. Reference JEDEC MS-012 variation AC.



PLASTIC SMALL-OUTLINE PACKAGE

0,51 0,35 ⊕0,25⊛ 1,27 8 14 0,15 NOM 5,60 8,20 5,00 7,40 \bigcirc Gage Plane ₽ 0,25 7 1 1,05 0,55 0°-10° Δ 0,15 0,05 Seating Plane — 2,00 MAX 0,10PINS ** 14 16 20 24 DIM 10,50 10,50 12,90 15,30 A MAX A MIN 9,90 9,90 12,30 14,70 4040062/C 03/03

NOTES: A. All linear dimensions are in millimeters.

NS (R-PDSO-G**)

14-PINS SHOWN

- B. This drawing is subject to change without notice.
- C. Body dimensions do not include mold flash or protrusion, not to exceed 0,15.



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